

Product/process change notification

PCN N° 2022-079-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Introduction of an additional assembly location at HANA Semiconductor (Ayutthaya) Co., Ltd. for products in PG-DSO-16

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-02-08
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



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Products affected

Please refer to attached affected product list "PCN_2022-079-A_[customer-no].pdf"

Detailed change information

Subject

Introduction of an additional assembly location at HANA Semiconductor (Ayutthaya) Co., Ltd. for products in PG-DSO-16.

Reason

Expansion of assembly and test capacity to cover increasing customer demand, and enable flexible manufacturing.

Description

<u>Old</u>

<u>New</u>

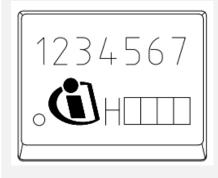
Assembly Location

 ATX Assembly & Test (Shanghai) Ltd., Shanghai, China

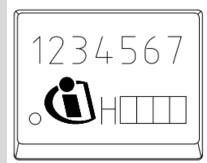
- ATX Assembly & Test (Shanghai) Ltd., Shanghai, China or
- Hana Semiconductor (Ayutthaya) Co., Ltd, Ayutthaya, Thailand

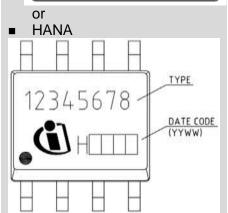
Assembly Site Code Marking

ATX



ATX







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▶ Product identification

Traceability assured via internal part number. No change in SP ordering number.

- ► Impact of change
- ▶ NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.
- ▶ NO change in package outline dimensions.
- ▶ NO change of existing Infineon specifications and datasheet parameters.
- **▶** Attachments

"PCN_2022-079-A_[customer-no].pdf" 2_cip22079A

affected product list qualification report

- ▶ Time schedule
 - Final qualification report

available

First samples available

2023-03-31

Intended start of delivery

2023-05-01 or earlier after customer release

If you have any questions, please do not hesitate to contact your local sales office.

RESTRICTED

Qualification Test Report



Date: 2022-04-06

Introduction of an Additional Assembly And Final Test Location at HANA Semiconductor (Ayutthaya, Thailand) Co., Ltd. for Products in PG-DSO-16 (Au wire).

Reason for choosing the following test vehicles:

OS2614353: representative product with B6CA / SPT5 Wafer technology chip in DSO-16 package using 25um AU-wire

Scope of qualification: Expansion of assembly and test capacity to cover increasing customer demand, and enable flexible manufacturing.

Assessment of Q-Results: PASS

Stress test	Abbreviation	Test conditions	Readout	OS2614353	OS2614353	OS2614355
				fails / stressed	fails / stressed	fails / stressed
MSL Preconditioning JESD22-A113	PC	MSL 3 reflow at 260°C	0h	0 / 231	0 / 231	0 / 231
High Temperature Storage Life JESD22-A103	HTSL	Ta = 150°C	1000 h	0/77	0/77	0/77
Unbiased HAST JESD22-A102	UHAST	with preconditioning Ta = 130°C RH = 85%	PC & 96 h	0/77	0/77	0/77
Temperature Humidity Bias JESD22-A118	ТНВ	with preconditioning Ta = 85°C RH = 85% V = Vmax	PC & 1000 h	0/77	0/77	0/77
Temperature Cycling JESD22-A104	тс	with preconditioning Ta min = -55°C Ta max = +150°C	PC & 1000 x	0/77	0/77	0/77
Electrostatic Charge Device Model JS-002	ESD (CDM)			Class C3 (>1000V)	Refer to OS2614353	Refer to OS2614353

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